

--9. (new) The device of claim 8, wherein said reinforcing pads are generally X-shaped and have four of said first solder balls thereon, each of said four first solder balls being at a respective distal end thereof.

A<sup>2</sup>  
cont.  
--10. (new) The device of claim 8, wherein said reinforcing pads are generally V-shaped and have at least two of said first solder balls thereon, each of said at least two first solder balls being at a respective distal end thereof.

--11. (new) The device of claim 8, further comprising plural second solder balls on said mounting surface and not on said reinforcing pads.

--12. (new) The device of claim 8, wherein said periphery of said reinforcing pads adjacent to said plural ones of said first solder balls, when seen in the plan view of said mounting surface, is no more than semicircular.--

REMARKS

The specification and abstract have been amended to make editorial changes therein to place the application in condition for allowance at the time of the next Official Action.

Claims 1-7 were pending. These have been replaced with new claims 8-12. Consideration and allowance of the new claims are respectfully requested.